US00D485277S

(12) **United States Design Patent**
Huang

(10) **Patent No.: US D485,277 S**
(45) **Date of Patent: ** Jan. 13, 2004**

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(54) **COMPUTER MAINFRAME FRONT PANEL**

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(73) Assignee: **Thermaltake Technology Co., Ltd.**, Taipei Hsien (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/174,548**

(22) Filed: **Jan. 22, 2003**

(30) **Foreign Application Priority Data**

Dec. 27, 2002 (TW) 91307614

(51) **LOC (7) Cl.** **14-02**
(52) **U.S. Cl.** **D14/444**
(58) **Field of Search** D14/441–446; D13/162, 184, 199; 312/223.2; 361/690–696

(56) **References Cited**

U.S. PATENT DOCUMENTS

D454,133 S * 3/2002 Yang D14/441
D464,357 S * 10/2002 Chien et al. D14/444

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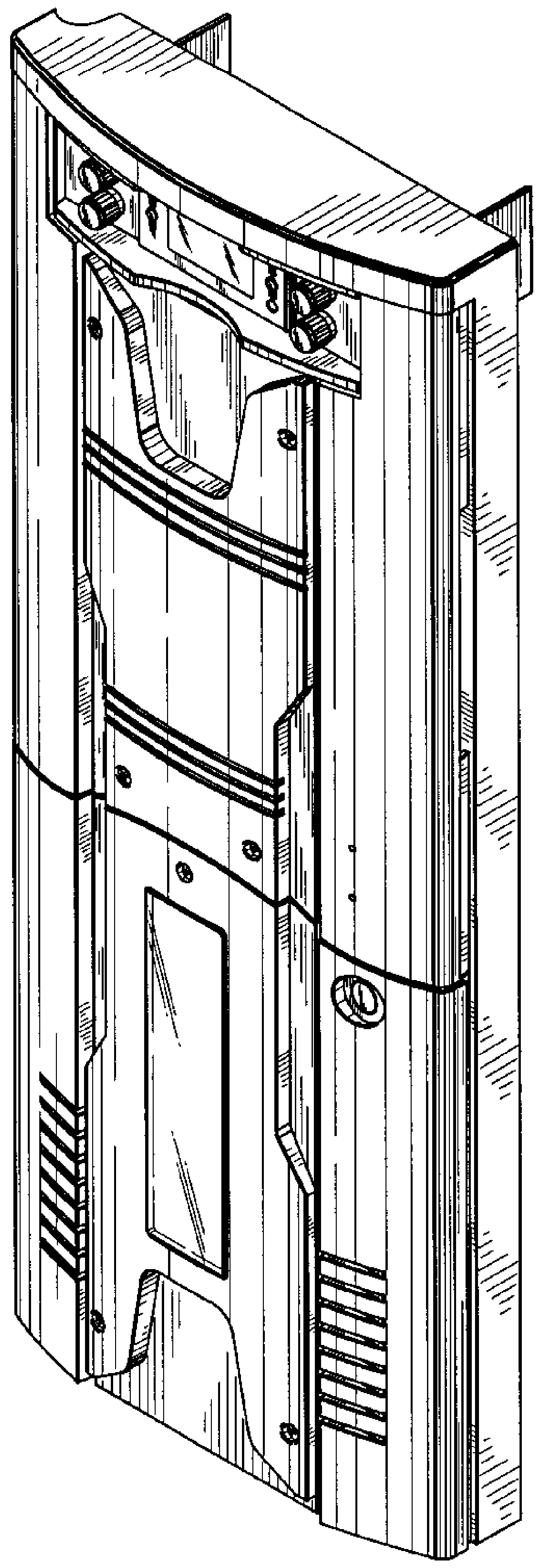
(57) **CLAIM**

The ornamental design for a computer mainframe front panel, as shown and described.

DESCRIPTION

FIG. **1** is a top, front and right side perspective view of a computer mainframe front panel showing my new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



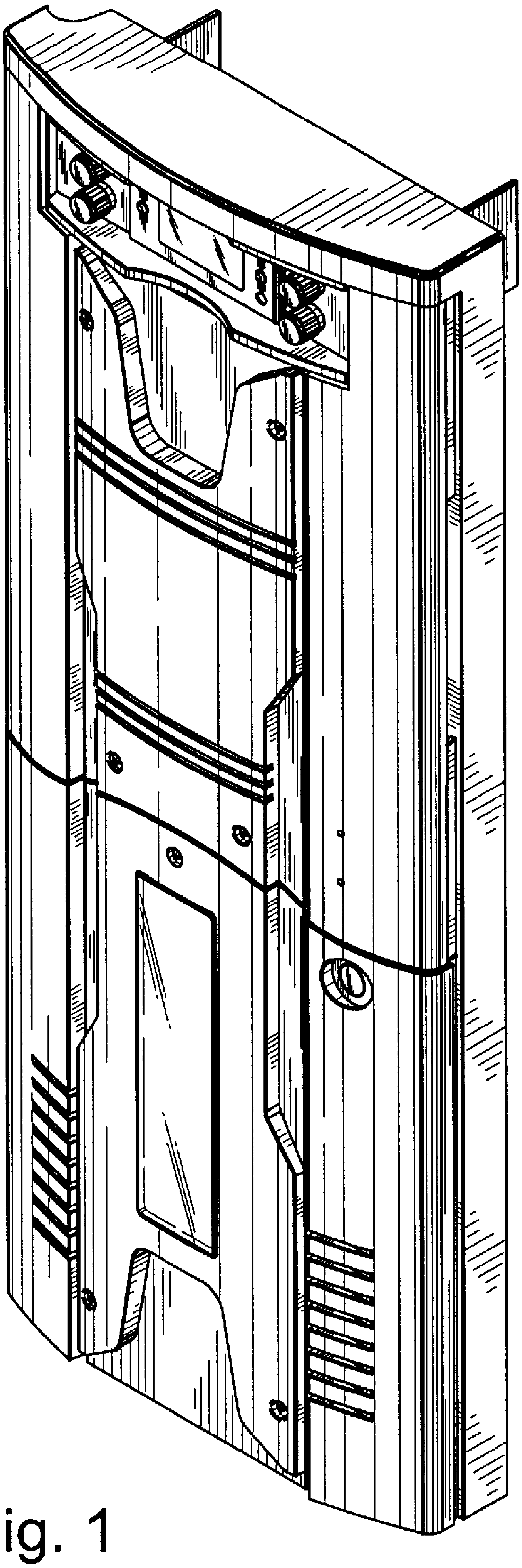


Fig. 1

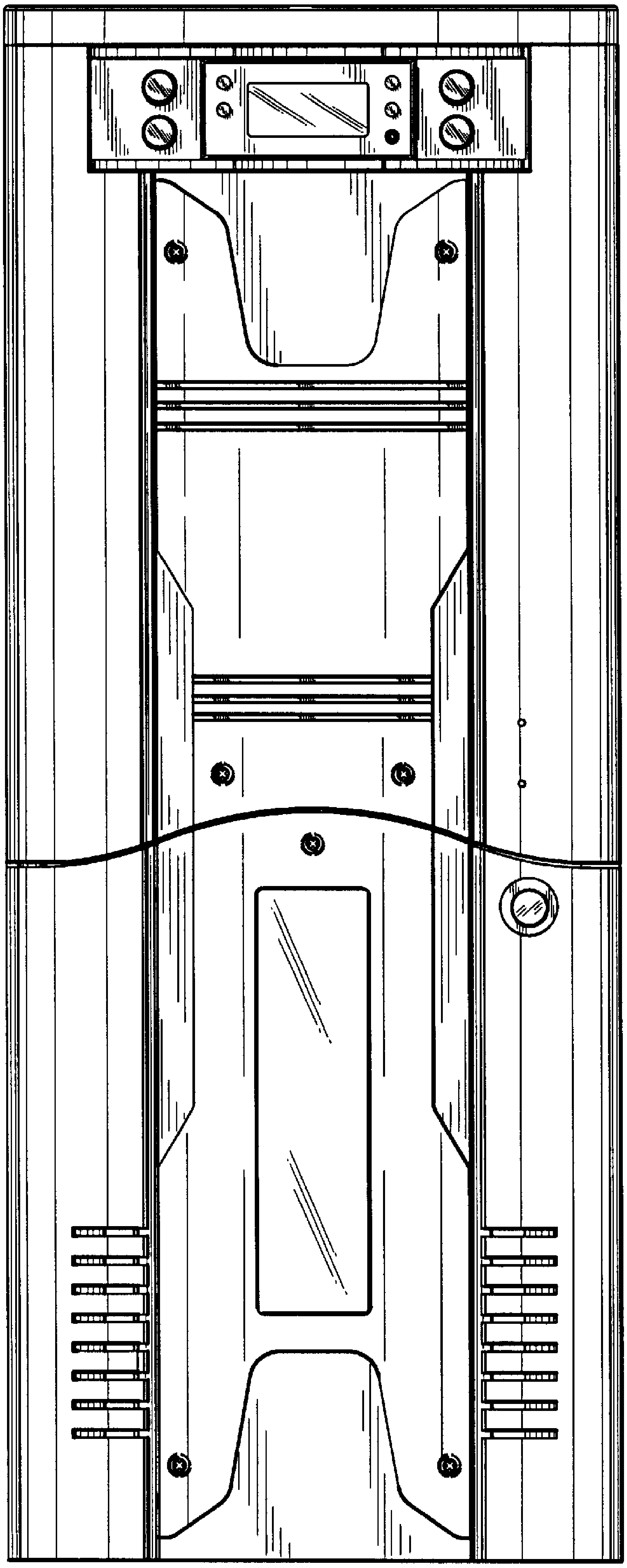


Fig. 2

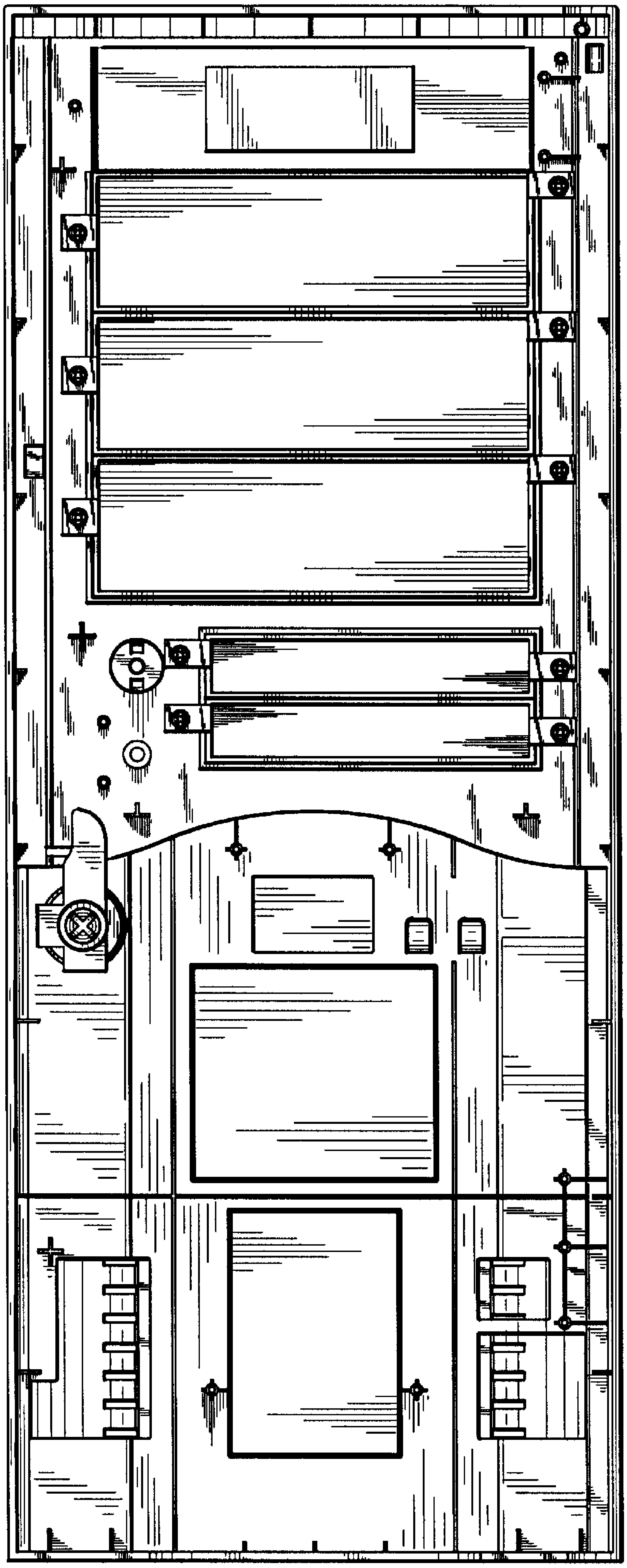


Fig. 3

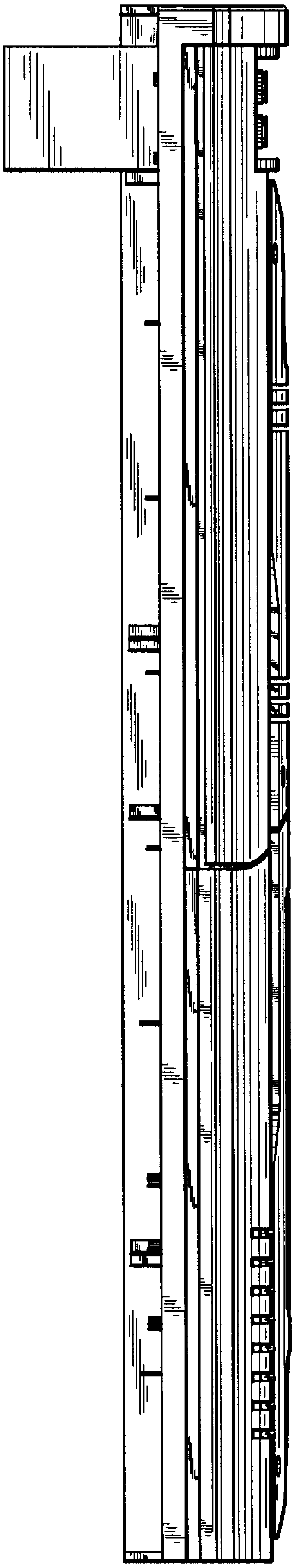


Fig. 4

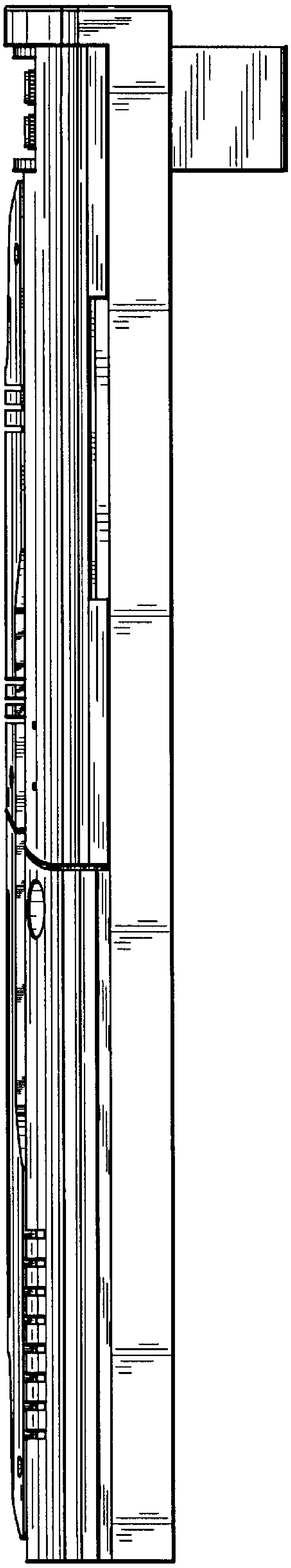


Fig. 5

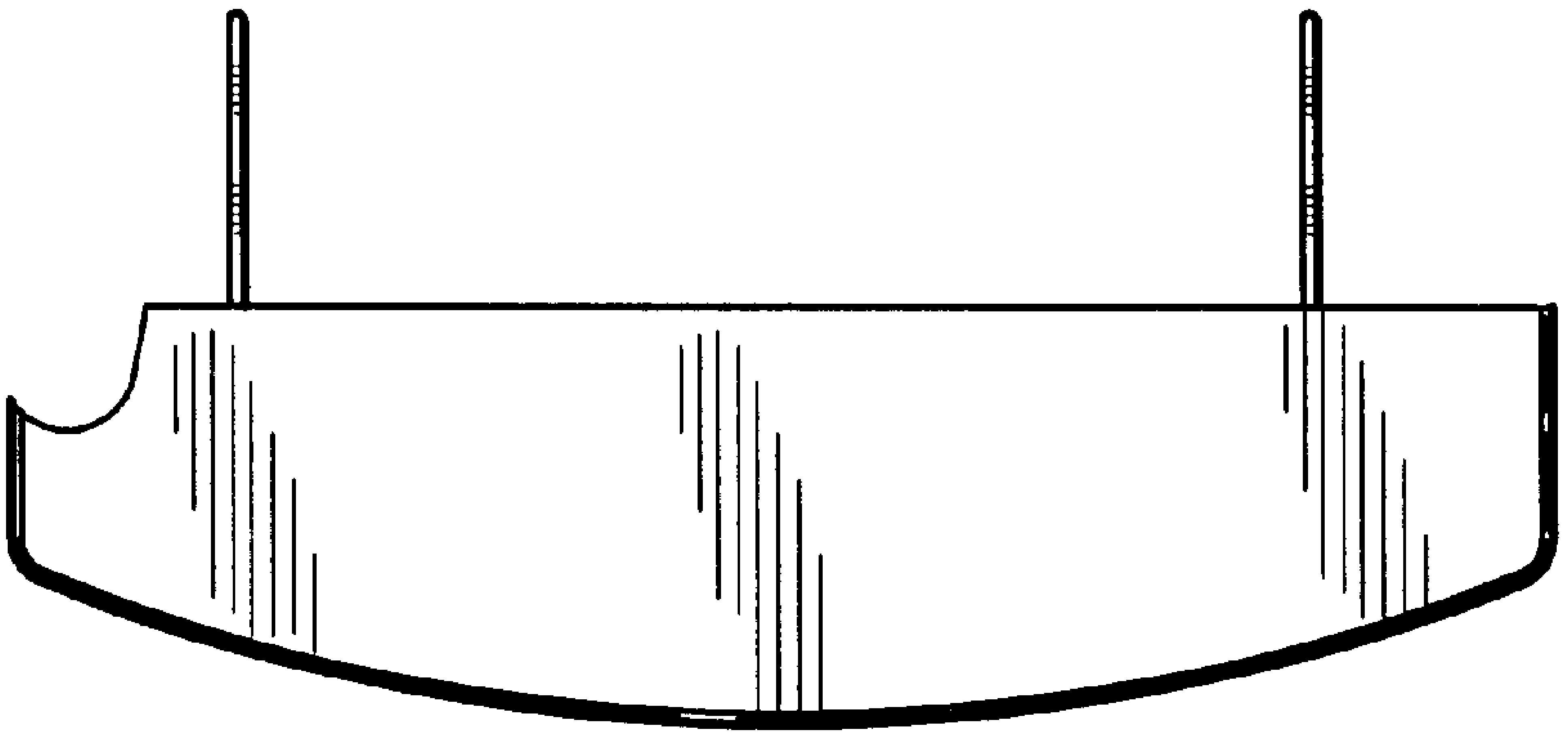


Fig. 6

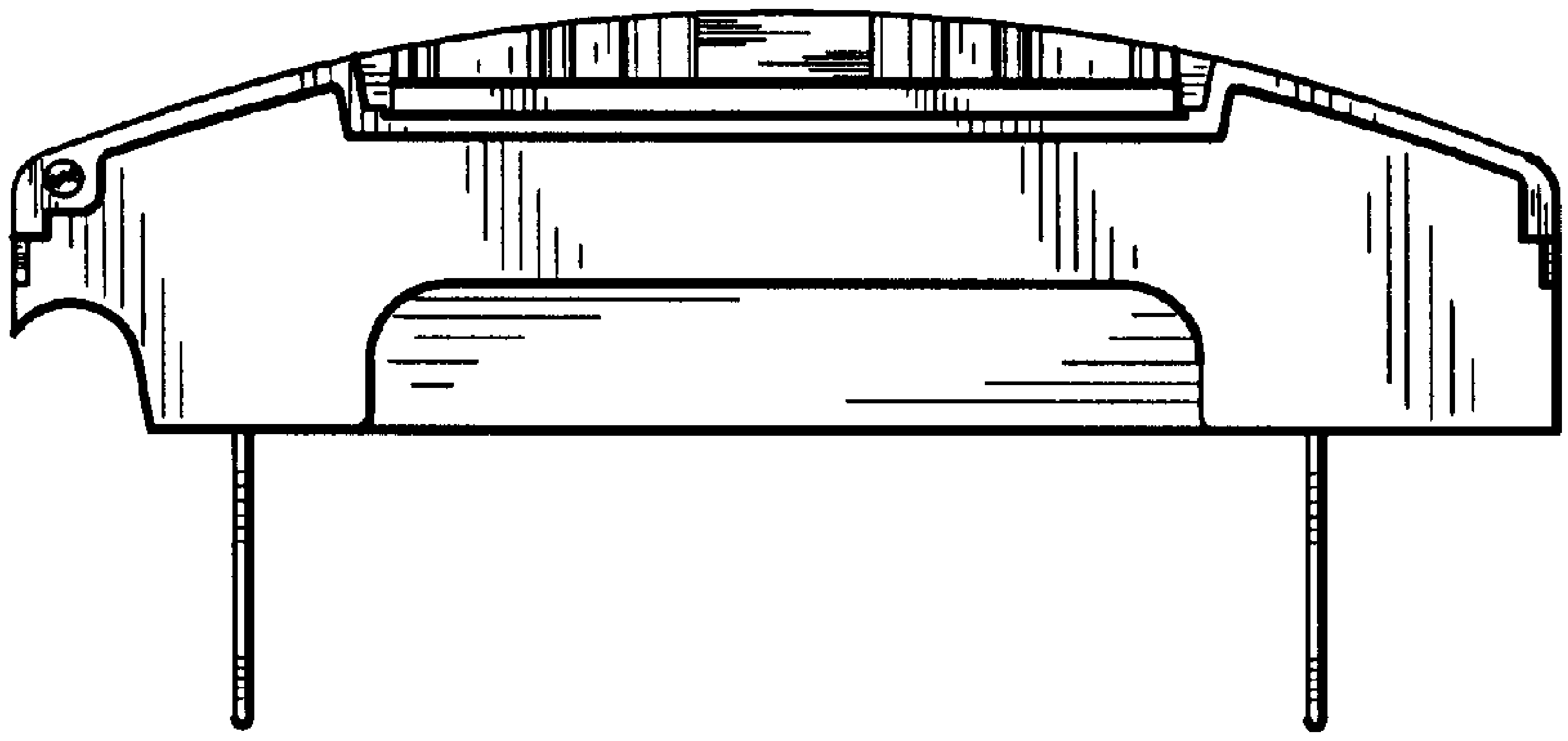


Fig. 7